











LM2593HV

SNVS082E - DECEMBER 2001 - REVISED MAY 2016

LM2593HV SIMPLE SWITCHER® Power Converter 150-kHz, 2-A Step-Down Voltage Regulator

Features

- 3.3-V, 5-V, and Adjustable Output Versions
- Adjustable Version Output Voltage Range: 1.2 V to 57 V ±4% Maximum Over Line and Load Conditions
- **Ensured 2-A Output Load Current**
- Available in 7-Pin TO-220 and TO-263 (Surface-Mount) Package
- Input Voltage Range up to 60 V
- 150-kHz Fixed Frequency Internal Oscillator
- Shutdown and Soft-Start
- Out-of-Regulation Error Flag
- Error Flag Delay
- Low Power Standby Mode: Io, Typically 90 µA
- High Efficiency
- Thermal Shutdown and Current-Limit Protection

Applications

- Simple High-Efficiency Step-Down (Buck) Regulators
- Efficient Preregulator for Linear Regulators
- **On-Card Switching Regulators**
- Positive-to-Negative Converters

3 Description

The LM2593HV series of regulators are monolithic integrated circuits that provide all the active functions for a step-down (buck) switching regulator, capable of driving a 2-A load with excellent line and load regulation. These devices are available in fixed output voltages of 3.3-V, 5-V, and an adjustable output version.

This series of switching regulators is similar to the LM2592HV with additional supervisorv performance features.

Requiring minimum number of components, these regulators are simple to use and include internal frequency compensation, improved line and load specifications, fixed-frequency oscillator, Shutdown/Soft-start, output error flag, and flag delay.

The LM2593HV operates at a switching frequency of 150 kHz, thus allowing smaller sized filter components than what would be needed with lower frequency switching regulators. Available in a standard 7-pin TO-220 package with several different lead bend options, and a 7-pin TO-263 surface-mount package.

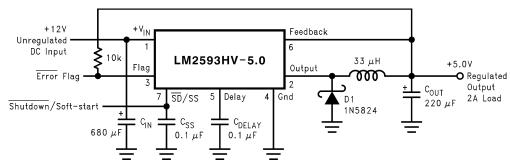
Other features include a specified ±4% tolerance on output voltage under all conditions of input voltage and output load conditions, and ±15% on the oscillator frequency. External shutdown is included, featuring typically 90-µA standby current. Selfprotection features include a two stage current limit for the output switch and an overtemperature shutdown for complete protection under fault conditions.

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
I MOEOOLIV	TO-263 (7)	10.10 mm × 8.89 mm
LM2593HV	TO-220 (7)	14.99 mm × 10.16 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Typical Application (Fixed Output Voltage Versions)



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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

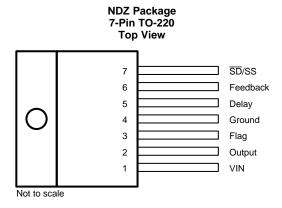
Changes from Revision D (December 2011) to Revision E

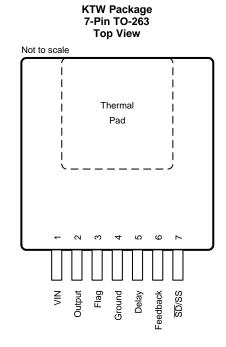
Page

Added ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and



5 Pin Configuration and Functions





Pin Functions

PIN		TYPE ⁽¹⁾	DECODITION
NO.	NAME	IYPE	DESCRIPTION
1	V _{IN}	I	This is the positive input supply for the IC switching regulator. A suitable input bypass capacitor must be present at this pin to minimize voltage transients and to supply the switching currents needed by the regulator.
2	Output	0	Internal switch. The voltage at this pin switches between approximately (+ $V_{IN} - V_{SAT}$) and approximately -0.5 V, with a duty cycle of V_{OUT}/V_{IN} .
3	Flag	0	Error flag: Open-collector output that goes active low (≤1 V) when the output of the switching regulator is out of regulation (less than 95% of its nominal value). In this state it can sink maximum 3 mA. When not low, it can be pulled high to signal that the output of the regulator is in regulation (power good). During power-up, it can be programmed to go high after a certain delay as set by the Delay pin (Pin 5). The maximum rating of this pin must not be exceeded, so if the rail to which it will be pulled up to is higher than 45 V, a resistive divider must be used instead of a single pullup resistor, as indicated in <i>Test Circuits</i> .
4	Ground	_	Circuit ground.
5	Delay	0	This sets a programmable power-up delay from the moment that the output reaches regulation, to the high signal output (power good) on Pin 3. A capacitor on this pin starts charging up by means on an internal (3 μ A) current source when the regulated output rises to within 5% of its nominal value. Pin 3 goes high (with an external pullup) when the voltage on the capacitor on Pin 5 exceeds 1.3 V. The voltage on this pin is clamped internally to about 1.7 V. If the regulated output drops out of regulation (less than 95% of its nominal value), the capacitor on Pin 5 is rapidly discharged internally and Pin 3 is forced low in about 1/1000th of the set power-up delay time. (2)
6	Feedback	ı	Senses the regulated output voltage to complete the feedback loop. This pin is directly connected to the Output for the fixed voltage versions, but is set to 1.23 V by means of a resistive divider from the output for the adjustable version. If a feedforward capacitor is used (adjustable version), then a negative voltage spike is generated on this pin whenever the output is shorted. This happens because the feedforward capacitor cannot discharge fast enough, and because one end of it is dragged to Ground, the other end goes momentarily negative. To prevent the energy rating of this pin from being exceeded, a small-signal Schottky diode to Ground is recommended for DC input voltages above 40 V whenever a feedforward capacitor is present (see <i>Test Circuits</i>). Feedforward capacitor values larger than 0.1 µF are not recommended for the same reason, whatever be the DC input voltage.

⁽¹⁾ G = Ground, I = Input, O = Output

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⁽²⁾ If any of these pins are not used, the respective pin can be left open.



Pin Functions (continued)

	PIN		PIN TYPE ⁽¹⁾		DESCRIPTION
NO.	NAME	I TPE'	DESCRIPTION		
7	SD/SS	I	Shutdown/Soft-start: The regulator is in shutdown mode, drawing about 90 μA, when this pin is driven to a low level (≤ 0.6 V), and is in normal operation when this Pin is left floating (internal pull-up) or driven to a high level (≥ 2 V). The typical value of the threshold is 1.3 V and the pin is internally clamped to a maximum of about 7 V. If it is driven higher than the clamp voltage, it must be ensured by means of an external resistor that the current into the pin does not exceed 1 mA. The duty cycle is minimum (0%) if this Pin is below 1.8 V, and increases as the voltage on the pin is increased. The maximum duty cycle (100%) occurs when this pin is at 2.8 V or higher. So adding a capacitor to this pin produces a soft-start feature. An internal current source charges the capacitor from zero to its internally clamped value. The charging current is about 5 μA when the pin is below 1.3 V but is reduced to only 1.6 μA above 1.3 V, so as to allow the use of smaller soft-start capacitors. (2)		

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT	
Maximum supply voltage, \	/ _{IN}			63	V	
SD/SS pin input voltage (2)				6	V	
Delay pin voltage ⁽²⁾				1.5	V	
Flag pin voltage			-0.3	45	V	
Feedback pin voltage			-0.3	25	V	
Output voltage to ground, steady-state				-1	V	
Power dissipation			Internall	y limited		
	Chaokaga	Vapor phase (60 s)		215		
Lead temperature	S package	Infrared (10 s)		245		
	T package, soldering	T package, soldering (10 s)		260]	
Maximum junction tempera	aximum junction temperature			150	°C	
Storage temperature, T _{stq}		-65	150	°C		

⁽¹⁾ Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESI)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 (1)(2)	±2000	V

⁽¹⁾ JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

	MIN	MAX	UNIT
Supply voltage	4.5	60	V
T _J Temperature	-40	125	°C

⁽²⁾ Voltage internally clamped. If clamp voltage is exceeded, limit current to a maximum of 1 mA.

⁽²⁾ The human body model is a 100-pF capacitor discharged through a 1.5-k resistor into each pin.



6.4 Thermal Information

		LM25		
	THERMAL METRIC ⁽¹⁾	NDZ (TO-220)	KTW (TO-263)	UNIT
		7 PINS	7 PINS	
$R_{\theta JA}$			50 ⁽³⁾	
	Junction-to-ambient thermal resistance	50 ⁽²⁾	30 ⁽⁴⁾	°C/W
			20 ⁽⁵⁾	
R _{θJC(top)}	Junction-to-case (top) thermal resistance	2	2	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	_	_	°C/W
ΨЈТ	Junction-to-top characterization parameter	_	_	°C/W
ΨЈВ	Junction-to-board characterization parameter	_	_	°C/W
R ₀ JC(bot)	Junction-to-case (bottom) thermal resistance	_	_	°C/W

- For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report, SPRA953.
- (2) Junction to ambient thermal resistance (no external heat sink) for the package mounted TO-220 package mounted vertically, with the leads soldered to a printed-circuit board with (1 oz) copper area of approximately 1 in².
- (3) Junction to ambient thermal resistance with the TO-263 package tab soldered to a single-sided printed-circuit board with 0.5 in² of (1 oz) copper area.
- (4) Junction to ambient thermal resistance with the TO-263 package tab soldered to a single-sided printed-circuit board with 2.5 in² of (1 oz) copper area.
- (5) Junction to ambient thermal resistance with the TO-263 package tab soldered to a double-sided printed-circuit board with 3 in² of (1 oz) copper area on the LM2593HVS side of the board, and approximately 16 in² of copper on the other side of the printed-circuit board.

6.5 Electrical Characteristics

 $T_J = 25^{\circ}$ C, $V_{IN} = 12$ V for the 3.3-V, 5-V, and adjustable versions, and $I_{LOAD} = 500$ mA (unless otherwise noted)

PARAMETER		TEST CONDIT	TIONS	MIN ⁽¹⁾	TYP ⁽²⁾	MAX ⁽¹⁾	UNIT
lb	Feedback bias current	Adjustable version only, VFB = 1	Adjustable version only, VFB = 1.3 V		10	100	nA
f _O	Oscillator frequency ⁽³⁾	$T_J = 25^{\circ}C$		127	150	173	kHz
10	Oscillator frequency ($T_J = -40$ °C to 125°C		110		173	KIIZ
		I _{OUT} = 2 A; no diode, inductor	$T_J = 25^{\circ}C$		1.1	1.3	
V _{SAT}	Saturation voltage	or capacitor connected to output pin (4); Feedback pin removed from output and connected to 0 V to force the output transistor switch ON (5)	$T_{J} = -40^{\circ}\text{C to } 125^{\circ}\text{C}$			1.4	V
	Max duty cycle (ON)		Feedback pin removed from output and connected to 0 V to force the output transistor switch ON		100%		
DC	Min duty cycle (OFF)	12 V for the 3.3-V, 5-V, and the	Feedback pin removed from output and connected to 12 V for the 3.3-V, 5-V, and the adjustable versions to force the output transistor switch OFF		0%		
		Peak current; no diode,	$T_J = 25^{\circ}C$	2.4	3	3.7	
I _{CLIM}	Switch current limit	inductor or capacitor connected to output pin; Feedback pin removed from output and connected to 0 V to force the output transistor switch ON	T _J = -40°C to 125°C	2.3		4	Α
IL	Output leakage current	12 V for the 3.3-V, 5-V, and the			5	30	mA
IQ	Operating quiescent current	SD and SS pin open, Feedback output and connected to 12 V fo the adjustable version to force the switch OFF	r the 3.3-V, 5-V, and		5	10	mA

⁽¹⁾ All limits specified at room temperature unless otherwise noted. All room temperature limits are 100% production tested. All limits at temperature extremes are ensured via correlation using standard Statistical Quality Control (SQC) methods. All limits are used to calculate Average Outgoing Quality Level (AOQL).

⁽²⁾ Typical numbers are at 25°C and represent the most likely norm.

⁽³⁾ The switching frequency is reduced when the second stage current limit is activated. The amount of reduction is determined by the severity of current overload.

⁽⁴⁾ No diode, inductor or capacitor connected to output pin.

⁽⁵⁾ Feedback pin removed from output and connected to 0 V to force the output transistor switch ON.



Electrical Characteristics (continued)

 $T_J = 25$ °C, $V_{IN} = 12$ V for the 3.3-V, 5-V, and adjustable versions, and $I_{LOAD} = 500$ mA (unless otherwise noted)

	PARAMETER	TEST CO	ONDITIONS	MIN ⁽¹⁾	TYP ⁽²⁾	MAX ⁽¹⁾	UNIT
	SD and SS pin = 0 V,		T _J = 25°C		90	200	^
I _{STBY}	Standby quiescent current	V _{IN} = 60 V	$T_J = -40$ °C to 125°C			250	μA
SHUTDO	OWN AND SOFT-START CONTROL	•					
V	Chuideum threehold valte as	Low (shutdown mode)			1.3	0.6	V
V_{SD}	Shutdown threshold voltage	High (soft-start mode)				2	V
.,	Coff start walks we	V _{OUT} = 20% of nominal out	tput voltage		2		
V_{SS}	Soft-start voltage	V _{OUT} = 100% of nominal output voltage			3		V
I _{SD}	Shutdown current	V _{SHUTDOWN} = 0.5 V			5	10	μA
I _{SS}	Soft-start current	V _{Soft-start} = 2.5 V			1.5	5	μA
	Regulator dropout detector	Low (flag ON)			96%		
	Threshold voltage	Low (flag ON)		92%		98%	
V _{FSAT}	Flag output saturation voltage	$I_{SINK} = 3 \text{ mA}, V_{DELAY} = 0.5$	V		0.3		μA
I _{FL}	Flag output leakage current	V _{FLAG} = 60 V		0.7	0.3	1	V
	Delay pin threshold voltage	Low (flag ON), high (flag O	PFF) and V _{OUT} regulated	1.21	1.25	1.29	V
	Delay pin source current	V _{DELAY} = 0.5 V			3	6	μA
	Delay pin saturation	Low (flag ON)		350	70	400	mV

6.6 Electrical Characteristics - 3.3-V Version

 $T_J = 25^{\circ}C$ (unless otherwise noted)

	PARAMETER	TEST C	MIN	TYP	MAX	UNIT	
SYSTEM PARAMETERS							
	0	$4.75 \text{ V} \le \text{V}_{IN} \le 60 \text{ V},$	T _J = 25°C	3.168	3.3	3.432	V
V _{OUT}	Output voltage	$0.2 \text{ A} \le I_{\text{LOAD}} \le 2 \text{ A}$		3.135		3.465	
η	Efficiency	V _{IN} = 12 V, I _{LOAD} = 2 A			76%		

6.7 Electrical Characteristics – 5-V Version

 $T_J = 25^{\circ}C$ (unless otherwise noted)

	PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
	$7 \text{ V} \leq \text{V}_{\text{IN}} \leq 60 \text{ V},$	$T_J = 25^{\circ}C$	4.8	5	5.2	\/	
	Output voltage	0.2 A ≤I _{LOAD} ≤ 2 A	$T_J = -40$ °C to 125°C	4.75		5.25	, v
η	Efficiency	V _{IN} = 12 V, I _{LOAD} = 2 A			81%		

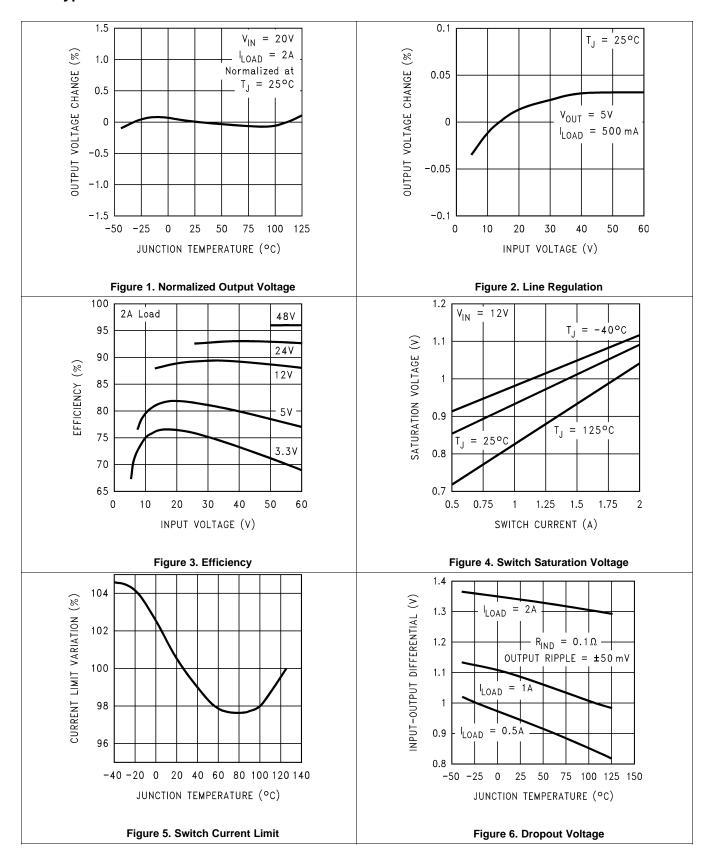
6.8 Electrical Characteristics – Adjustable Voltage Version

 $T_J = 25$ °C (unless otherwise noted)

	PARAMETER	TEST CONDITI	MIN	TYP	MAX	UNIT	
		$4.5 \text{ V} \le \text{V}_{\text{IN}} \le 60 \text{ V},$	T _J = 25°C	1.193	1.23	1.267	
VFB	T B T eedback voltage	0.2 A ≤ I _{LOAD} ≤ 2 Å, V _{OUT} programmed for 3 V (see <i>Test Circuits</i>)	$T_{J} = -40^{\circ}\text{C to } 125^{\circ}\text{C}$	1.18		1.28	V
η	Efficiency	$V_{IN} = 12 \text{ V}, V_{OUT} = 3 \text{ V}, I_{LOAD} = 2 \text{ A}$			75%		

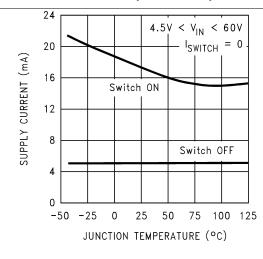


6.9 Typical Characteristics





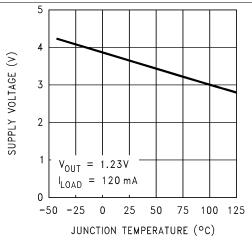
Typical Characteristics (continued)



120 = 25°C and 125°C 100 -40°C 80 CURRENT (µA) 60 $V_{\overline{SD}/SS} = 0V$ 40 20 0 10 20 30 40 50 60 0 SUPPLY VOLTAGE (V)

Figure 7. Operating Quiescent Current





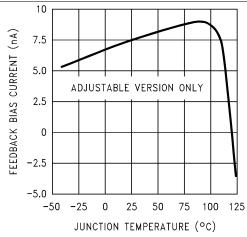
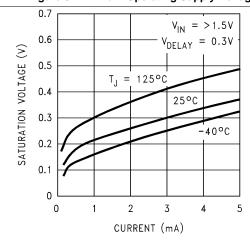


Figure 9. Minimum Operating Supply Voltage

Figure 10. Feedback Pin Bias Current



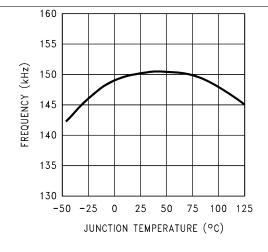


Figure 11. Flag Saturation Voltage

Figure 12. Switching Frequency



Typical Characteristics (continued)

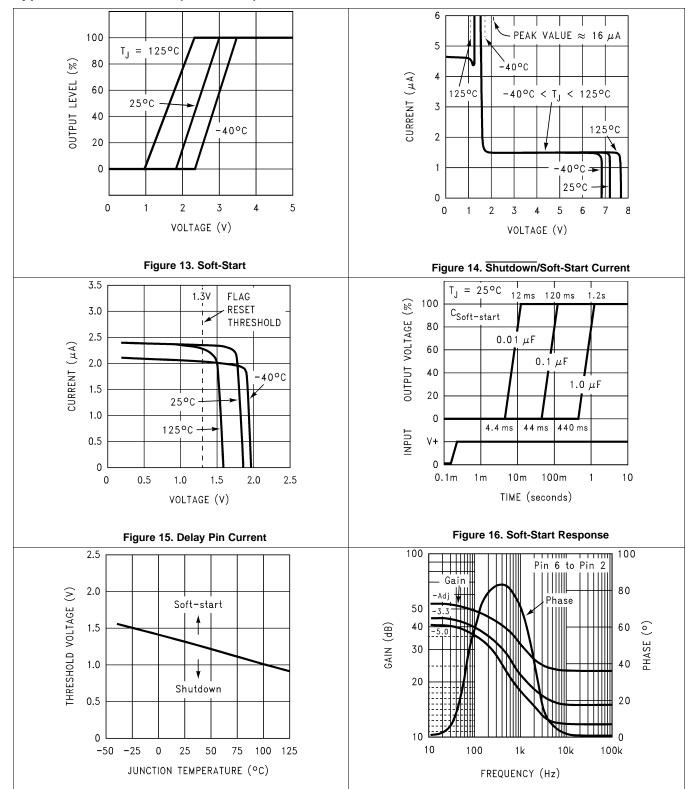
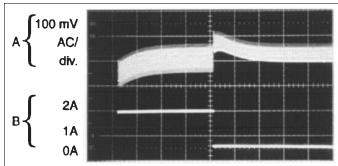


Figure 17. Shutdown/Soft-Start Threshold Voltage

Figure 18. Internal Gain-Phase Characteristics

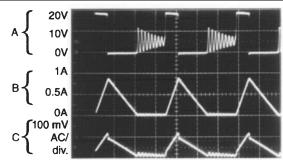


Typical Characteristics (continued)



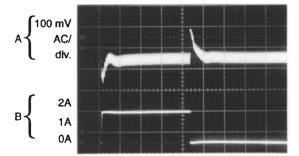
Horizontal Time Base: 2 μ s/div. $V_{IN}=20$ V, $V_{OUT}=5$ V, $I_{LOAD}=2$ A, L=32 μ H, $C_{OUT}=220$ μ F, C_{OUT} ESR = 50 m Ω Output Pin Voltage, 10 V/div. Inductor Current, 1 A/div. Output Ripple Voltage, 50 mV/div.

Figure 19. Continuous Mode Switching Waveforms



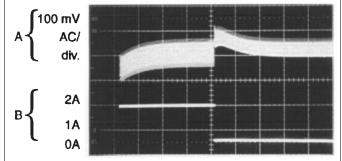
Horizontal Time Base: 2 μs/div. $V_{IN}=20~V,~V_{OUT}=5~V,~I_{LOAD}=500~mA,~L=10~\mu H,~C_{OUT}=330~\mu F,~C_{OUT}~ESR=50~m\Omega$ Output Pin Voltage, 10 V/div. Inductor Current, 0.5 A/div. Output Ripple Voltage, 100 mV/div.

Figure 20. Discontinuous Mode Switching Waveforms



Horizontal Time Base: 50 µs/div. $V_{IN}=20~V,~V_{OUT}=5~V,~I_{LOAD}=500~mA~to~2~A,~L=32~\mu H,~C_{OUT}=220~\mu F,~C_{OUT}~ESR=50~m\Omega$ Output Voltage, 100 mV/div. (AC) 500-mA to 2-A Load Pulse

Figure 21. Load Transient Response for Continuous Mode



Horizontal Time Base: 200 μ s/div. $V_{IN}=20$ V, $V_{OUT}=5$ V, $I_{LOAD}=500$ mA to 2 A, L = 10 μ H, $C_{OUT}=330$ μ F, C_{OUT} ESR = 50 m Ω Output Voltage, 100 mV/div. (AC) 500-mA to 2-A Load Pulse

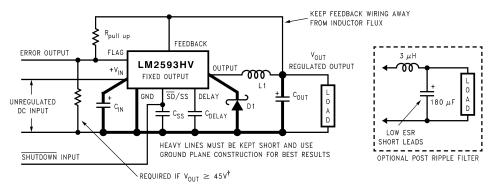
Figure 22. Load Transient Response for Discontinuous Mode

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7 Parameter Measurement Information

7.1 Test Circuits



Component Values shown are for $V_{IN} = 15 \text{ V}$,

 $V_{OUT} = 5 \text{ V}, I_{LOAD} = 2 \text{ A}.$

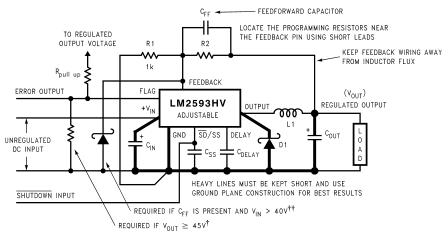
C_{IN} — 470-μF, 50-V aluminum electrolytic Nichicon *PM Series*

C_{OUT} — 220-µF, 25-V aluminum electrolytic Nichcon *PM Series*

D1 — 3.3-A, 60-V Schottky Rectifier, 21DQ06 (international rectifier)

L1 — 33 µH, see Inductors Selection Procedure

Figure 23. Fixed Output Voltage Versions



Select R_1 to be approximately 1 k Ω , use a 1% resistor for best stability.

Component values shown are for $V_{IN} = 20 \text{ V}$,

 $V_{OUT} = 10 \text{ V}, I_{LOAD} = 2 \text{ A}.$

C_{IN} — 470-µF, 35-V aluminum electrolytic Nichicon *PM Series*

 C_{OUT} — 220- μF , 35-V aluminum electrolytic Nichicon *PM Series*

D1 — 3.3-A, 60-V Schottky Rectifier, 21DQ06 (international rectifier)

L1 — 47 µH, see *Inductors Selection Procedure*

 $R_1 - 1 k\Omega, 1\%$

R₂ — 7.15 k, 1%

 C_{FF} — 3.3 nF

Typical Values

 C_{SS} — 0.1 μF

 $C_{DELAY} - 0.1 \, \mu F$

 $R_{PULL\ UP}$ — 4.7 k (use 22 k if V_{OUT} is \geq 45 V)

† Resistive divider is required to avoid exceeding maximum rating of 45 V, 3 mA on or into flag pin.

†† Small signal Schottky diode to prevent damage to feedback pin by negative spike when output is shorted (C_{FF} not being able to discharge immediately will drag feedback pin below ground). Required if $V_{IN} > 40 \text{ V}$.

Figure 24. Adjustable Output Voltage Versions

Product Folder Links: LM2593HV

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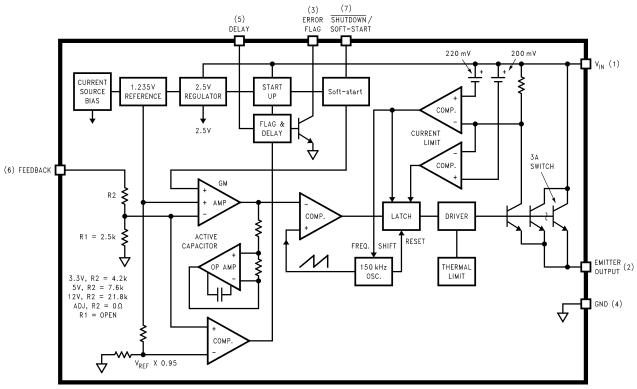


8 Detailed Description

8.1 Overview

The LM2593HV SIMPLE SWITCHER® regulator is an easy-to-use, non-synchronous, step-down DC-DC converter with a wide input voltage range up to 60 V. It is capable of delivering up to 2-A DC load current with excellent line and load regulation. These devices are available in fixed output voltages of 3.3-V, 5-V, and an adjustable output version. The family requires few external components and the pin arrangement was designed for simple, optimum PCB layout.

8.2 Functional Block Diagram



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8.3 Feature Description

8.3.1 Undervoltage Lockout

Some applications require the regulator to remain off until the input voltage reaches a predetermined voltage. Figure 25 contains a undervoltage lockout circuit for a buck configuration, while Figure 26 and Figure 27 are for the inverting types (only the circuitry pertaining to the undervoltage lockout is shown). Figure 25 uses a Zener diode to establish the threshold voltage when the switcher begins operating. When the input voltage is less than the Zener voltage, resistors R1 and R2 hold the Shutdown/Soft-Start pin low, keeping the regulator in the shutdown mode. As the input voltage exceeds the Zener voltage, the Zener conducts, pulling the Shutdown/Soft-Start pin high, allowing the regulator to begin switching. The threshold voltage for the undervoltage lockout feature is approximately 1.5 V greater than the Zener voltage.



Feature Description (continued)

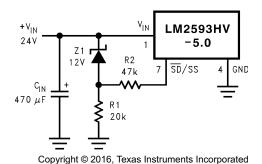


Figure 25. Undervoltage Lockout for a Buck Regulator

Figure 26 and Figure 27 apply the same feature to an inverting circuit. Figure 26 features a constant threshold voltage for turnon and turnoff (Zener voltage plus approximately 1 V). If hysteresis is needed, the circuit in Figure 27 has a turnon voltage which is different than the turnoff voltage. The amount of hysteresis is approximately equal to the value of the output voltage. Because the \overline{SD}/SS pin has an internal 7-V Zener clamp, R2 is needed to limit the current into this pin to approximately 1 mA when Q1 is on.

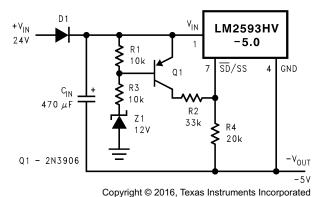


Figure 26. Undervoltage Lockout Without Hysteresis for an Inverting Regulator

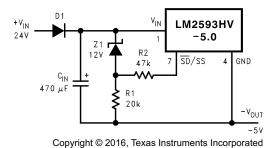


Figure 27. Undervoltage Lockout With Hysteresis for an Inverting Regulator



Feature Description (continued)

8.3.2 Negative Voltage Charge Pump

Occasionally a low current negative voltage is needed for biasing parts of a circuit. A simple method of generating a negative voltage using a charge pump technique is shown in Figure 28. This unregulated negative voltage is approximately equal to the positive input voltage (minus a few volts), and can supply up to a 600 mA of output current. There is a requirement however, that there be a minimum load of 1.2 A on the regulated positive output for the charge pump to work correctly. Also, resistor R1 is required to limit the charging current of C1 to some value less than the LM2593HV current limit. This method of generating a negative output voltage without an additional inductor can be used with other members of the SIMPLE SWITCHER® family, using either the buck or boost topology.

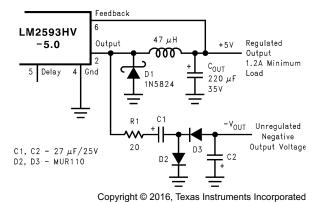


Figure 28. Charge Pump for Generating a Low-Current, Negative Output Voltage

8.3.3 Shutdown/Soft-Start

This reduction in start-up current is useful in situations where the input power source is limited in the amount of current it can deliver. In some applications, soft-start can be used to replace undervoltage lockout or delayed start-up functions. If a very slow output voltage ramp is desired, the soft-start capacitor can be made much larger. Many seconds or even minutes are possible. If only the shutdown feature is needed, the soft-start capacitor can be eliminated.

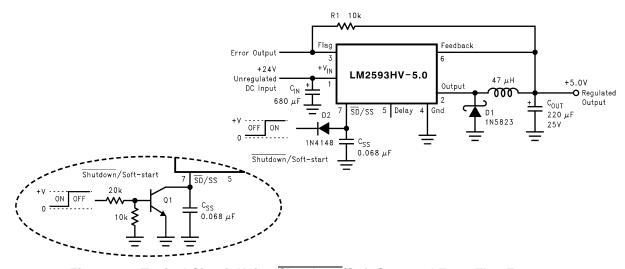


Figure 29. Typical Circuit Using Shutdown/Soft-Start and Error Flag Features



Feature Description (continued)

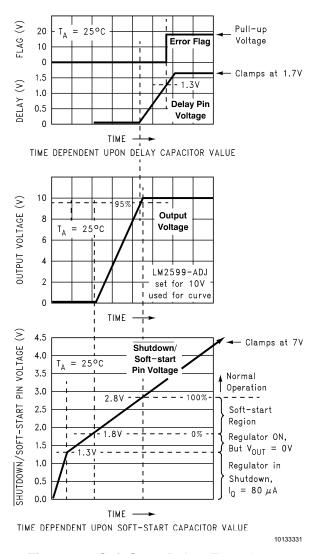


Figure 30. Soft-Start, Delay, Error Output

8.4 Device Functional Modes

8.4.1 Shutdown Mode

The Shutdown/Soft-start pin provides electrical ON and OFF control for the LM2593HV. When the voltage of this pin is less than 0.6 V, the device is in shutdown mode. The typical standby current in this mode is 90 μA.

8.4.2 Active Mode

When the Shutdown/Soft-start pin is left floating or pull above 2 V, the device starts switching and the output voltage rises until it reaches a normal regulation voltage.



9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

9.1.1 Feedforward Capacitor, CFF

(Adjustable output voltage version only)

A feedforward capacitor shown across R2 in *Test Circuits* is used when the output voltage is greater than 10 V or when C_{OUT} has a very low ESR. This capacitor adds lead compensation to the feedback loop and increases the phase margin for better loop stability. If the output voltage ripple is large (>5% of the nominal output voltage), this ripple can be coupled to the feedback pin through the feedforward capacitor and cause the error comparator to trigger the error flag. In this situation, adding a resistor, R_{FF}, in series with the feedforward capacitor, approximately 3 times R1, attenuates the ripple voltage at the feedback pin.

9.1.2 Input Capacitor, CIN

A low-ESR aluminum or tantalum bypass capacitor is needed between the input pin and ground pin. It must be placed near the regulator using short leads. This capacitor prevents large voltage transients from appearing at the input, and provides the instantaneous current needed each time the switch turns on. The important parameters for the Input capacitor are the voltage rating and the RMS current rating. Because of the relatively high RMS currents flowing in a buck regulator's input capacitor, this capacitor must be chosen for its RMS current rating rather than its capacitance or voltage ratings, although the capacitance value and voltage rating are directly related to the RMS current rating. The voltage rating of the capacitor and its RMS ripple current capability must never be exceeded.

9.1.3 Output Capacitor, Cour.

An output capacitor is required to filter the output and provide regulator loop stability. Low impedance or low ESR Electrolytic or solid tantalum capacitors designed for switching regulator applications must be used. When selecting an output capacitor, the important capacitor parameters are; the 100-kHz Equivalent Series Resistance (ESR), the RMS ripple current rating, voltage rating, and capacitance value. For the output capacitor, the ESR value is the most important parameter. The ESR must generally not be less than 100 mW or there will be loop instability. If the ESR is too large, efficiency and output voltage ripple are effected. So ESR must be chosen carefully.

9.1.4 Catch Diode

Buck regulators require a diode to provide a return path for the inductor current when the switch turns off. This must be a fast diode and must be placed close to the LM2593HV using short leads and short printed-circuit traces.

Because of their very fast switching speed and low forward voltage drop, Schottky diodes provide the best performance, especially in low output voltage applications (5 V and lower). Ultra-fast recovery, or high-efficiency rectifiers are also a good choice, but some types with an abrupt turnoff characteristic may cause instability or EMI problems. Ultra-fast recovery diodes typically have reverse recovery times of 50 ns or less. The diode must be chosen for its average or RMS current rating and maximum voltage rating. The voltage rating of the diode must be greater than the DC input voltage (not the output voltage).

Product Folder Links: *LM2593HV*

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Application Information (continued)

9.1.5 Inverting Regulator

The circuit in Figure 31 converts a positive input voltage to a negative output voltage with a common ground. The circuit operates by bootstrapping the regulator's ground pin to the negative output voltage, then grounding the feedback pin, the regulator senses the inverted output voltage and regulates it. This example uses the LM2593HV 5-V to generate a -5-V output, but other output voltages are possible by selecting other output voltage versions, including the adjustable version. Because this regulator topology can produce an output voltage that is either greater than or less than the input voltage, the maximum output current greatly depends on both the input and output voltage. To determine how much load current is possible before the internal device current limit is reached (and power limiting occurs), the system must be evaluated as a buck-boost configuration rather than as a buck. The peak switch current in amperes, for such a configuration is given as Equation 1.

$$I_{PEAK} {=} \, I_{LOAD} \, {\times} \Bigg(\frac{V_{IN} + V_{OUT}}{V_{IN}} \Bigg) {+} \, \frac{V_{IN} \times V_{OUT} \times 10^6}{2 \times L \times f \times \left(V_{IN} + V_{OUT}\right)} \\$$

where

L is in µH

The maximum possible load current I_{LOAD} is limited by the requirement that $I_{PEAK} \le I_{CLIM}$. While checking for this, take I_{CLIM} to be the lowest possible current limit value (minimum across tolerance and temperature is 2.3 A for the LM2593HV). Also to account for inductor tolerances, take the minimum value of Inductance for L in Equation 1 (typically 20% less than the nominal value). Further, the above equation disregards the drop across the switch and the diode. This is equivalent to assuming 100% efficiency, which is never so. Therefore expect I_{PFAK} to be an additional 10-20% higher than calculated from Equation 1. See also Application Note AN-1197 Selecting Inductors for Buck Converters (SNVA038) for examples based on positive to negative configuration. The maximum voltage appearing across the regulator is the absolute sum of the input and output voltage. This must be limited to a maximum of 60 V. In this example, when converting 20 V to -5 V, the regulator would see 25 V between the input pin and ground pin. The LM2593HV has a maximum input voltage rating of 60 V. An additional diode is required in this regulator configuration. Diode D1 is used to isolate input voltage ripple or noise from coupling through the CIN capacitor to the output, under light or no load conditions. Also, this diode isolation changes the topology to closely resemble a buck configuration thus providing good closed-loop stability. A Schottky diode is recommended for low input voltages, (because of its lower voltage drop) but for higher input voltages, a IN5400 diode could be used. Because of differences in the operation of the inverting regulator, the standard design procedure is not used to select the inductor value. In the majority of designs, a 33-µH, 4-A inductor is the best choice. Capacitor selection can also be narrowed down to just a few values. This type of inverting regulator can require relatively large amounts of input current when starting up, even with light loads. Input currents as high as the LM2593HV current limit (approximately 4 A) are needed for 2 ms or more, until the output reaches its nominal output voltage. The actual time depends on the output voltage and the size of the output capacitor. Input power sources that are current limited or sources that can not deliver these currents without getting loaded down, may not work correctly. Because of the relatively high start-up currents required by the inverting topology, the soft-start feature shown in Figure 31 is recommended. Also shown in Figure 31 are several shutdown methods for the inverting configuration. With the inverting configuration, some level shifting is required, because the ground pin of the regulator is no longer at ground, but is now at the negative output voltage. The shutdown methods shown accept ground referenced shutdown signals.

Application Information (continued)

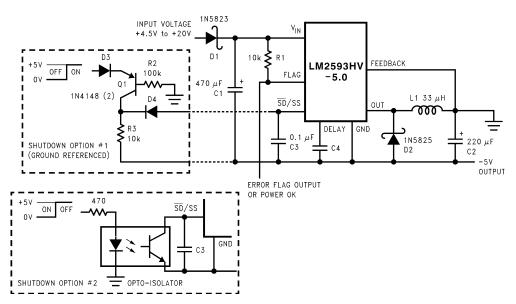


Figure 31. Inverting -5 V Regulator With Shutdown and Soft-Start

9.2 Typical Application

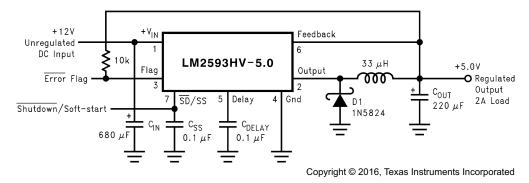


Figure 32. LM2593HV 5-V Application Schematic

9.2.1 Design Requirements

Table 1 lists the example values for this typical application.

Table 1. Application Example Parameters

DESIGN PARAMETER	EXAMPLE VALUE
Regulated output voltage (3.3 V, 5 V, or adjustable), V _{OUT}	5 V
Maximum input voltage, V _{IN(max)}	24 V
Maximum load current, I _{LOAD(max)}	1 A
Switching frequency, F	Fixed at a nominal 150 kHz

Product Folder Links: LM2593HV

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9.2.2 Detailed Design Procedure

9.2.2.1 Inductors Selection Procedure

See application note AN-1197 Selecting Inductors for Buck Converters (SNVA038) for detailed information on inductor selection. For a quick-start, see the nomographs provided in Figure 33 to Figure 35. To widen the choices to a more general selection of available inductors, the nomographs provide the required inductance and also the energy in the core expressed in microjoules (μ J), as an alternative to just prescribing custom parts. The following points must be highlighted:

- 1. The energy values shown on the nomographs apply to steady operation at the corresponding x-coordinate (rated maximum load current). However under start-up, without soft-start, or a short-circuit on the output, the current in the inductor momentarily and repetitively hits the current limit I_{CLIM} of the device, and this current could be much higher than the rated load, I_{LOAD}. This represents an overload situation, and can cause the inductor to saturate (if it has been designed only to handle the energy of steady operation). However most types of core structures used for such applications have a large inherent air gap (for example powdered iron types or ferrite rod inductors), and so the inductance does not fall off too sharply under an overload. The device is usually able to protect itself by not allowing the current to ever exceed I_{CLIM}. But if the DC input voltage to the regulator is over 40 V, the current can slew up so fast under core saturation, that the device may not be able to act fast enough to restrict the current. The current can then rise without limit till destruction of the device takes place. Therefore to ensure reliability, TI recommends, that if the DC input voltage exceeds 40 V, the inductor must always be sized to handle an instantaneous current equal to I_{CLIM} without saturating, irrespective of the type of core structure or material.
- 2. Use Equation 2 to calculate the energy under steady operation.

$$e = \frac{1}{2} \times L \times I_{PEAK}^2 \mu J$$

where

- L is in µH
- I_{PEAK} is the peak of the inductor current waveform with the regulator delivering I_{LOAD}

These are the energy values shown in the nomographs. See Example 1.

3. The energy under overload is Equation 3.

$$e = \frac{1}{2} \times L \times I_{CLIM}^2 \mu J$$

where

- L is in µH
- I_{PEAK} is the peak of the inductor current waveform with the regulator delivering I_{LOAD}
 (3)

If $V_{IN} > 40 \text{ V}$, the inductor must be sized to handle e_{CLIM} instead of the steady energy values. The worst case I_{CLIM} for the LM2593HV is 4 A. The energy rating depends on the inductance. See *Example 2*.

- 4. The nomographs were generated by allowing a greater amount of percentage current ripple in the inductor as the maximum rated load decreases (see Figure 36). This was done to permit the use of smaller inductors at light loads. However, Figure 36 shows only the *median* value of the current ripple. In reality there may be a great spread around this because the nomographs approximate the exact calculated inductance to standard available values. It is a good idea to refer to *AN-1197 Selecting Inductors for Buck Converters* (SNVA038) for detailed calculations if a certain maximum inductor current ripple is required for various possible reasons. Also consider the rather wide tolerance on the nominal inductance of commercial inductors.
- Figure 35 shows the inductor selection curves for the adjustable version. The y-axis is Et, in Vμs. It is the
 applied volts across the inductor during the ON time of the switch (V_{IN}-V_{SAT}-V_{OUT}) multiplied by the time for
 which the switch is on in μs. See Example 3.

9.2.2.1.1 Example 1: $V_{IN} \le 40 \text{ V}$, 5-V Version, $V_{IN} = 24 \text{ V}$, Output = 5 V at 1 A

 A first pass inductor selection is based upon inductance and rated maximum load current. Choose an inductor with the inductance value indicated by the nomograph (see Figure 34) and a current rating equal to the maximum load current. Therefore, quick-select a 68-μH, 1-A inductor (designed for 150-kHz operation) for this application.

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(2)



 Confirm that it is rated to handle 50 μJ (see Figure 34) by either estimating the peak current or by a detailed calculation as shown in AN-1197 Selecting Inductors for Buck Converters (SNVA038), and also that the losses are acceptable.

9.2.2.1.2 Example 2: $V_{IN} > 40 \text{ V}$, 5-V version, $V_{IN} = 48 \text{ V}$, Output = 5 V at 1.5 A

- 1. A first pass inductor selection is based upon inductance and the switch currrent limit. Choose an inductor with the inductance value indicated by the nomograph (see Figure 34) and a current rating equal to I_{CLIM}. Therefore, quick-select a 68-µH, 4-A inductor (designed for 150-kHz operation) for this application.
- 2. Confirm that it is rated to handle e_{CLIM} by the procedure shown in *AN-1197 Selecting Inductors for Buck Converters* (SNVA038) and that the losses are acceptable. Here e_{CLIM} is Equation 4.

$$e_{CLIM} = \frac{1}{2} \times 68 \times 4^2 = 544 \ \mu J$$
 (4)

9.2.2.1.3 Example 3: $V_{IN} \le 40 \text{ V}$, Adjustable Version, $V_{IN} = 20 \text{ V}$, Output = 10 V at 2 A

1. Because input voltage is less than 40 V, a first pass inductor selection is based upon inductance and rated maximum load current. Choose an inductor with the inductance value indicated by the nomograph Figure 35 and a current rating equal to the maximum load. But first calculate Et for the given application. The duty cycle is Equation 5.

$$D = \frac{V_{OUT} + V_{D}}{V_{IN} - V_{SAT} + V_{D}}$$

where

V_D is the drop across the catch diode (0.5 V for a Schottky)

So this yields Equation 6.

$$D = \frac{10 + 0.5}{20 - 1.5 + 0.5} = 0.55 \tag{6}$$

2. The switch ON time is calculated with Equation 7.

$$t_{ON} = \frac{D}{f} \times 10^6 \ \mu s$$

where

• f is the switching frequency in Hz (7)

So this yields Equation 8.

Et =
$$(V_{IN} - V_{SAT} - V_{OUT}) \times t_{ON}$$

= $(20 - 1.5 - 10) \times \frac{0.55}{150000} \times 10^6 \text{ V} \mu \text{ sec s}$
= $31.3 \text{ V} \mu \text{ sec s}$ (8)

- 3. Therefore, looking at Figure 33, quick-select a 47-µH, 2-A inductor (designed for 150-kHz operation) for this application.
- 4. Confirm that it is rated to handle 200 μJ (see Figure 35) by the procedure shown in *AN-1197 Selecting Inductors for Buck Converters* (SNVA038) and that the losses are acceptable. (If the DC input voltage had been greater than 40 V, consider e_{CLIM} as in Example 2).

This completes the simplified inductor selection procedure. For more general applications and better optimization, refer to AN-1197 Selecting Inductors for Buck Converters (SNVA038).

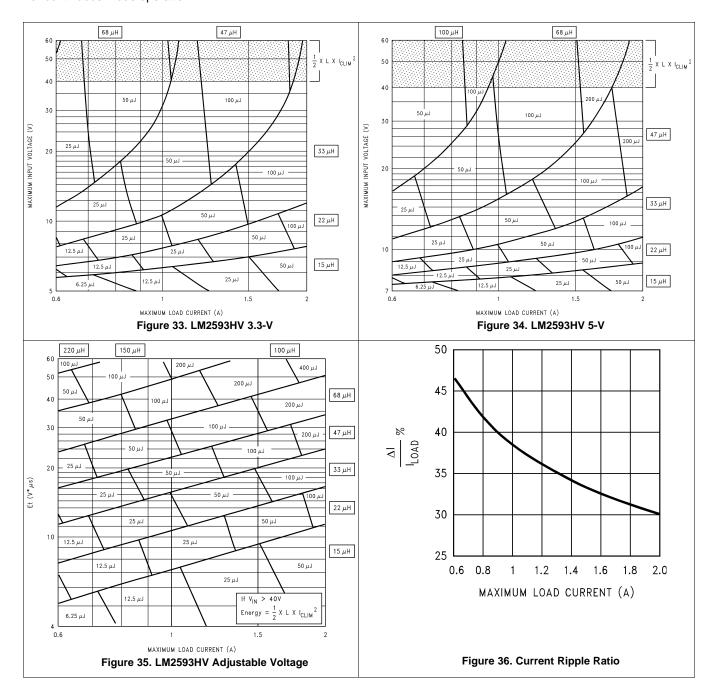
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9.2.3 Application Curves

For continuous mode operation





10 Power Supply Recommendations

The LM2593HV is designed to operate from an input voltage supply up to 60 V. This input supply must be well regulated and able to withstand maximum input current and maintain a stable voltage.

11 Layout

11.1 Layout Guidelines

As in any switching regulator, layout is very important. Rapid switching currents associated with wiring inductance can generate voltage transients which can cause problems. For minimal inductance and ground loops, with reference to *Functional Block Diagram*, the wires indicated by heavy lines must be wide printed-circuit traces and must be kept as short as possible. For best results, external components must be placed as close to the switcher IC as possible using ground plane construction or single-point grounding.

If open core inductors are used, take special care as to the location and positioning of this type of inductor. Allowing the inductor flux to intersect sensitive feedback, IC groundpath and C_{OUT} wiring can cause problems.

When using the adjustable version, take special care as to the location of the feedback resistors and the associated wiring. Physically place both resistors near the IC, and route the wiring away from the inductor, especially an open core type of inductor.

11.2 Layout Example

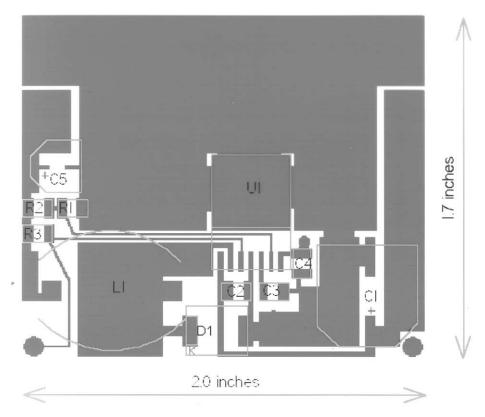


Figure 37. Top Side (Component Side) of PCB

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11.3 Thermal Considerations

The LM2593HV is available in two packages, a 5-pin TO-220 (T) and a 5-pin surface-mount TO-263 (S). The TO-220 package needs a heat sink under most conditions. The size of the heat sink depends on the input voltage, the output voltage, the load current, and the ambient temperature. Higher ambient temperatures require more heat sinking. The TO-263 surface-mount package tab is designed to be soldered to the copper on a printed-circuit board. The copper and the board are the heat sink for this package and the other heat-producing components, such as the catch diode and inductor. The PCB copper area that the package is soldered to must be at least 0.4 in², and ideally must have 2 or more square inches of 2-oz. (0.0028 in) copper. Additional copper area improves the thermal characteristics, but with copper areas greater than approximately 6 in², only small improvements in heat dissipation are realized. If further thermal improvements are needed, double-sided, multilayer PCB with large copper areas or airflow are recommended. The curves shown in Figure 38 show the LM2593HVS (TO-263 package) junction temperature rise above ambient temperature with a 2-A load for various input and output voltages. This data was taken with the circuit operating as a buck switching regulator with all components mounted on a PCB to simulate the junction temperature under actual operating conditions. This curve can be used for a quick check for the approximate junction temperature for various conditions, but be aware that there are many factors that can affect the junction temperature. When load currents higher than 2 A are used, double-sided or multilayer PCBs with large copper areas or airflow might be required, especially for high ambient temperatures and high output voltages. For the best thermal performance, wide copper traces and generous amounts of printed-circuit board copper must be used in the board layout. (One exception to this is the output (switch) pin, which must not have large areas of copper.) Large areas of copper provide the best transfer of heat (lower thermal resistance) to the surrounding air, and moving air lowers the thermal resistance even further. Package thermal resistance and junction temperature rise numbers are all approximate, and there are many factors that affect these numbers. Some of these factors include board size, shape, thickness, position, location, and even board temperature. Other factors are, trace width, total printed-circuit copper area, copper thickness, single- or double-sided, multilayer board, and the amount of solder on the board. The effectiveness of the PCB to dissipate heat also depends on the size, quantity, and spacing of other components on the board, as well as whether the surrounding air is still or moving. Furthermore, some of these components, such as the catch diode will add heat to the PCB and the heat can vary as the input voltage changes. For the inductor, depending on the physical size, type of core material, and the DC resistance, it could either act as a heat sink taking heat away from the board, or it could add heat to the board.

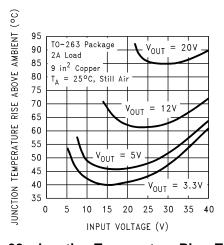


Figure 38. Junction Temperature Rise, TO-263

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12 Device and Documentation Support

12.1 Documentation Support

12.1.1 Related Documentation

For related documentation see the following:

AN-1197 Selecting Inductors for Buck Converters, SNVA038

12.2 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E™ Online Community TI's Engineer-to-Engineer (E2E) Community. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

12.3 Trademarks

E2E is a trademark of Texas Instruments.

SIMPLE SWITCHER is a registered trademark of Texas Instruments.

All other trademarks are the property of their respective owners.

12.4 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

12.5 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.





25-Jan-2016

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing		Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
LM2593HVS-3.3/NOPB	ACTIVE	DDPAK/ TO-263	KTW	7	45	Pb-Free (RoHS Exempt)	CU SN	Level-3-245C-168 HR	-40 to 125	LM2593HVS -3.3 P+	Samples
LM2593HVS-5.0/NOPB	ACTIVE	DDPAK/ TO-263	KTW	7	45	Pb-Free (RoHS Exempt)	CU SN	Level-3-245C-168 HR	-40 to 125	LM2593HVS -5.0 P+	Samples
LM2593HVS-ADJ	NRND	DDPAK/ TO-263	KTW	7	45	TBD	Call TI	Call TI	-40 to 125	LM2593HVS -ADJ P+	
LM2593HVS-ADJ/NOPB	ACTIVE	DDPAK/ TO-263	KTW	7	45	Pb-Free (RoHS Exempt)	CU SN	Level-3-245C-168 HR	-40 to 125	LM2593HVS -ADJ P+	Samples
LM2593HVSX-3.3/NOPB	ACTIVE	DDPAK/ TO-263	KTW	7	500	Pb-Free (RoHS Exempt)	CU SN	Level-3-245C-168 HR	-40 to 125	LM2593HVS -3.3 P+	Samples
LM2593HVSX-5.0/NOPB	ACTIVE	DDPAK/ TO-263	KTW	7	500	Pb-Free (RoHS Exempt)	CU SN	Level-3-245C-168 HR	-40 to 125	LM2593HVS -5.0 P+	Samples
LM2593HVSX-ADJ/NOPB	ACTIVE	DDPAK/ TO-263	KTW	7	500	Pb-Free (RoHS Exempt)	CU SN	Level-3-245C-168 HR	-40 to 125	LM2593HVS -ADJ P+	Samples
LM2593HVT-5.0/NOPB	ACTIVE	TO-220	NDZ	7	45	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM	-40 to 125	LM2593HVT -5.0 P+	Samples
LM2593HVT-ADJ/NOPB	ACTIVE	TO-220	NDZ	7	45	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM	-40 to 125	LM2593HVT -ADJ P+	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

25-Jan-2016

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM2593HVSX-3.3/NOPB	DDPAK/ TO-263	KTW	7	500	330.0	24.4	10.75	14.85	5.0	16.0	24.0	Q2
LM2593HVSX-5.0/NOPB	DDPAK/ TO-263	KTW	7	500	330.0	24.4	10.75	14.85	5.0	16.0	24.0	Q2
LM2593HVSX-ADJ/NOPB	DDPAK/ TO-263	KTW	7	500	330.0	24.4	10.75	14.85	5.0	16.0	24.0	Q2

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM2593HVSX-3.3/NOPB	DDPAK/TO-263	KTW	7	500	367.0	367.0	45.0
LM2593HVSX-5.0/NOPB	DDPAK/TO-263	KTW	7	500	367.0	367.0	45.0
LM2593HVSX-ADJ/NOPB	DDPAK/TO-263	KTW	7	500	367.0	367.0	45.0







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